UP Xtreme i11

bridge the gap

specification

UP Xtreme i11 Edge Compute Enabling Kit

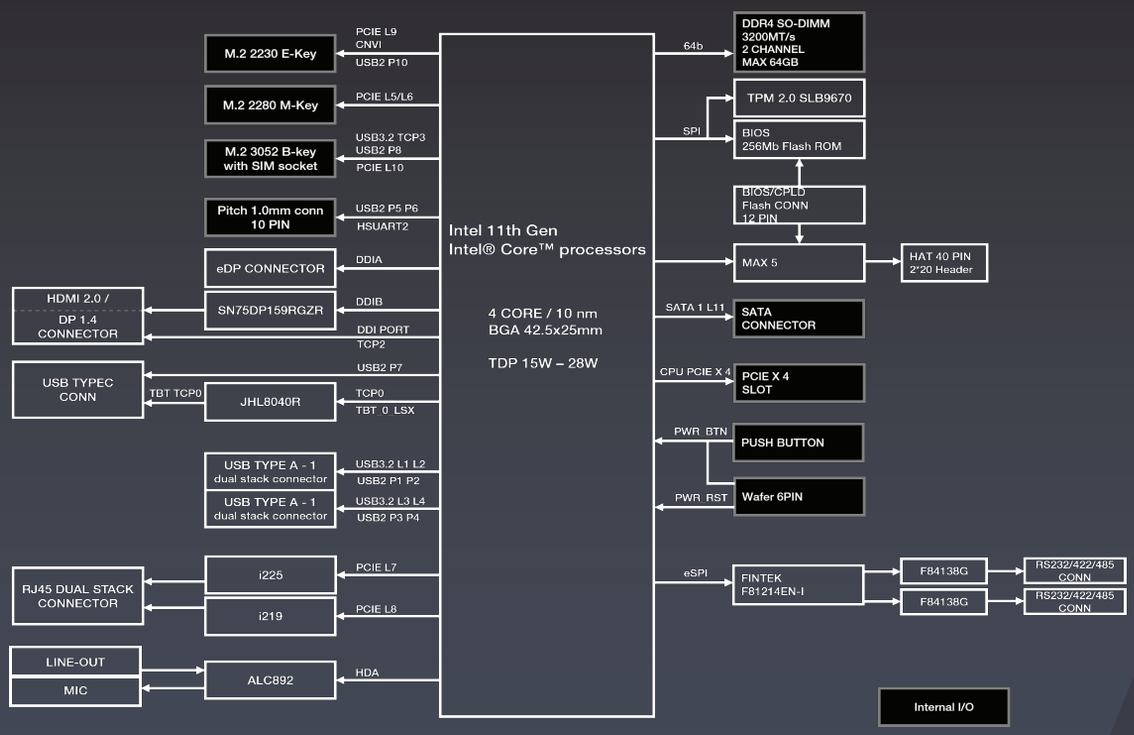
Introducing the next generation in edge computing with 5G capabilities to deliver seamless connectivity, powered by the latest Intel® 11th Gen Core™ processors with Iris® Xᵉ graphics.

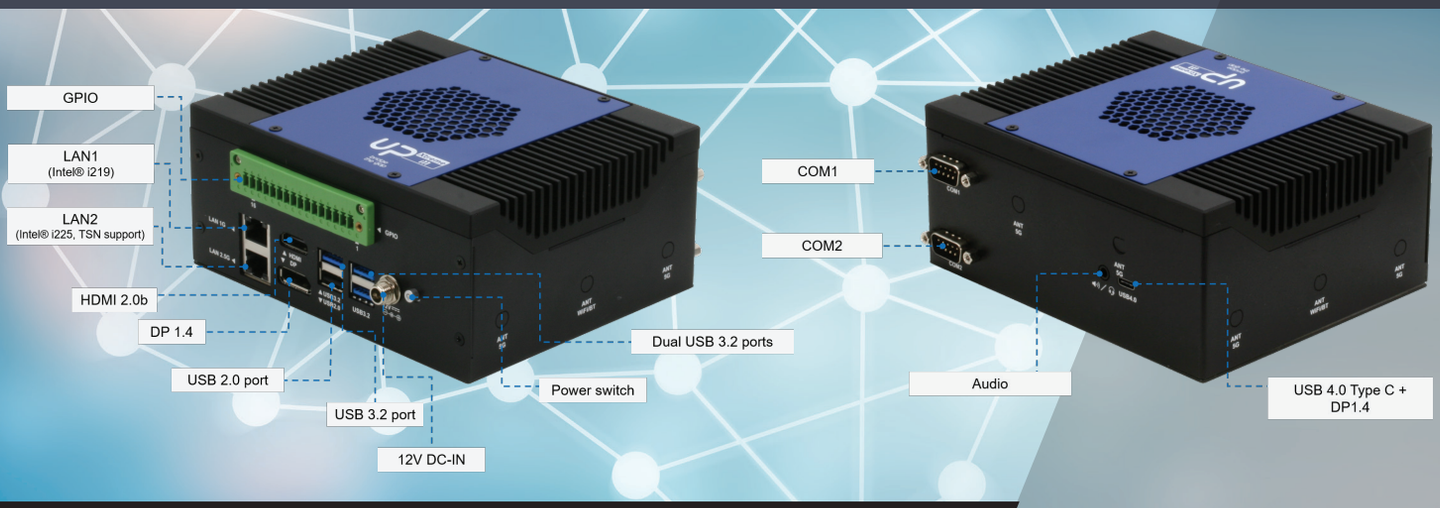
TECH SPECIFICATIONS

System	UP Xtreme i11 Edge
SoC	Intel® Core™ i7-1185GRE (up to 4.4 GHz) Intel® Core™ i5-1145GRE (up to 4.1 GHz) Intel® Core™ i3-1115GRE (up to 3.9 GHz) Intel® Celeron 6305E (up to 2.0 Ghz)
# of Cores	i3-1115GRE/ Celeron 6305E-Duo Core i7-1185GRE/i5-1145GRE-Quad Core
Graphics	Intel® Iris® Xe Graphics - i7-1185GRE/i5-1145GRE Intel® UHD Graphics for 11th Gen Intel® Processors-i3-1115GRE/ Celeron 6305E
VPU	Optional (via M.2 2280)
FPGA	Intel® FPGA Altera MAX 5
System memory	2x DDR4 2 channel SO-DIMM VERTICAL MAX 64GB @ 3200MT/s
Storage capacity	via 1x SATA 3.0 CONN with POWER CONN / 1xM.2 2280 M key (combo 2x PCIE[x1]) NVME
BIOS	UEFI
RTC	Yes
WAKE ON LAN (WoL)	Yes
WATCHDOG TIMER	Yes
PXE	Yes
Compatible OS	Microsoft Windows 10 full version, Yocto project 3.0/3.1 Kernel 5.4, Ubuntu 20.04 Kernel 5.8
Inference tookit	Intel® Distribution of OpenVINO™ toolkit 2021 R1
Supported Frameworks	TensorFlow, Caffe
Power Requirement	12V DC-IN (lockable connector)
Power Supply type	AT/ATX
Power Consumption	32W (typical)

Operating temp	Target 0-60°C
Storage temp	-40°F ~ 176°F (-40°C ~ 80°C)
Operating humidity	0% ~ 90% relative humidity, non-condensing
Certification	CE, FCC Class A, RoHS compliant
Display	1 (HDMI 2.0b) 1x DP + 1x DP 1.4 (via USB Type C) 1 x eDP (4K@60hz)
Audio	Audio Jack (Realtek ALC888S/ALC897 colay)
I/O	**USB:** 3x USB 3.2, 1x USB 4.0 (Thunderbolt Type C), 1x USB 2.0 Type A **UART**: 1 x HSUART (pin header) **Serial Port**: Fintek F81801, 2x RS232/422/485 **HDD interface:** 1 x SATA 3.0 **SIM Slot x1** **Others:** Phoenix: 3V3, 5V, GND, I2C, GPIO x8, PWM x2 Infineon TPM SLB9670 on board
Expansion Slot	1x M.2 2280 M key (support NVME SSD) 1x M.2 2230 E key 1x M.2 3052 B Key (USB 3.0 interface) with SIM 1x PCI-e[x4] (adapter board accessory required)
Connectivity	Ethernet via 1 x 1GbLAN (i219), 1x 2.5Gb LAN (i225), WiFi optional (via. M.2 2230) Bluetooth optional (via. M.2 2230) LTE/4G/5G optional (via. M.2 3052)
Cooling	Active heatsink
Package net weight	2.3kg
Gross weight	3.6kg
Product dimension	152 x 124 x 66.5 mm (5.98" x 4.88" x 2.61")
Package dimension	278 x 269 x 149 mm (10.94" x 10.59" x 5.86")
HS Code	8471500000
ECCN code	4A994
Country of Origin	Taiwan
Longivity	2035

block diagram





Artifical Intelligence on the edge

Expand your UP Xtreme i11 Compute Enabling Kit to fit your exact needs

M.2 2230 WiFi kit

Intel® Wireless-AC 9260
(802.11ac, Bluetooth 5.0)

UP AI Core XM 2280

AI hardware accelerator with
2x Intel® Movidius™ Myriad™ X